

40V PNP SURFACE MOUNT TRANSISTOR IN SOT89

Features

- Epitaxial Planar Die Construction
- Low Collector-Emitter Saturation Voltage
- Complementary NPN Type Available (2DD1766)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

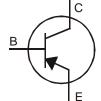
Mechanical Data

- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Solderable per MIL-STD-202, Method 208
 - Weight: 0.055 grams (approximate)

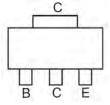
SOT89



Top View



Device Schematic



Top view Pin-Out

Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
2DB1188P-13	P23P	13	12	2,500
2DB1188Q-13	P23Q	13	12	2,500
2DB1188R-13	P23R	13	12	2,500

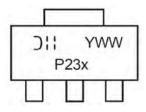
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com.

Marking Information

Notes:



P23x = Product Type Marking Code Where P23P = 2DB1188P P23Q = 2DB1188Q P23R = 2DB1188R DII = Manufacturers' code marking YWW = Date Code Marking Y = Last Digit of Year (ex: 1 = 2011) WW = Week Code (01 - 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-40	V
Collector-Emitter Voltage	V _{CEO}	-32	V
Emitter-Base Voltage	V _{EBO}	-6	V
Continuous Collector Current	lc	-2	A
Peak Pulse Collector Current (Note 5)	I _{CM}	-3	A

Thermal Characteristics (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	PD	1	W
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	125	°C/W
Thermal Resistance, Junction to Leads (Note 7)	R _{θJL}	19	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

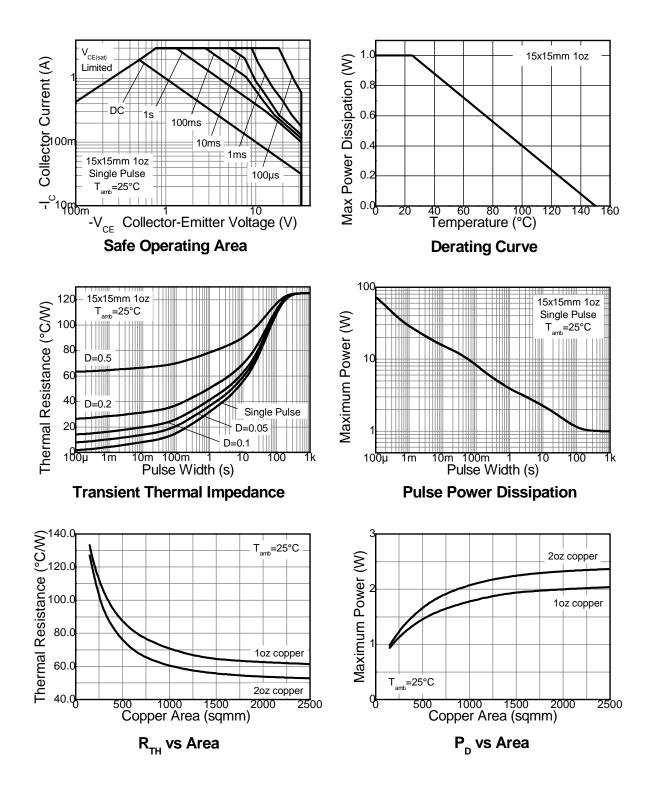
Notes:

Measured under pulsed conditions. Pulse width = 300µs. Duty cycle ≤ 2%.
For a device surface mounted on 15mm X 15mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions

7. Thermal resistance from junction to solder-point (at the end of the collector lead).



Thermal Characteristics

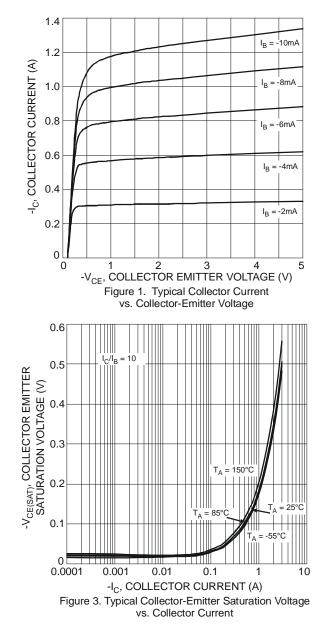


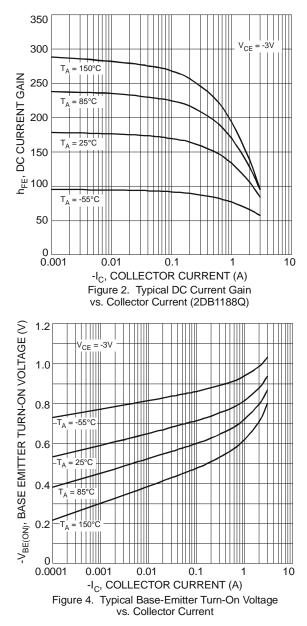


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (N	ote 5)						•
Collector-Base Breakdown Voltage		BV _{CBO}	-40		_	V	$I_{\rm C} = -100 \mu A, I_{\rm E} = 0$
Collector-Emitter Breakdown Voltage		BV _{CEO}	-32		_	V	$I_{\rm C} = -10 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage		BV _{EBO}	-6	_	_	V	$I_{\rm E} = -100 \mu A, I_{\rm C} = 0$
Collector Cutoff Current		Ісво			-100	nA	$V_{CB} = -20V, I_E = 0$
Emitter Cutoff Current		I _{EBO}			-100	nA	$V_{EB} = -5V, I_{C} = 0$
ON CHARACTERISTICS (No	te 5)						·
Collector-Emitter Saturation Voltage		V _{CE(sat)}	_	-0.35	-0.8	V	$I_{\rm C} = -2A, I_{\rm B} = -0.2A$
	2DB1188P		82		180		
DC Current Gain	2DB1188Q	h _{FE}	120	—	270	—	$V_{CE} = -3V, I_{C} = -0.5A$
	2DB1188R		180		390		
SMALL SIGNAL CHARACTE	RISTICS						
Current Gain-Bandwidth Product		f _T	_	120	_	MHz	$V_{CE} = -5V, I_C = -0.1A,$ f = 30MHz
Output Capacitance		C _{obo}		20		pF	V _{CB} = -10V, f = 1MHz

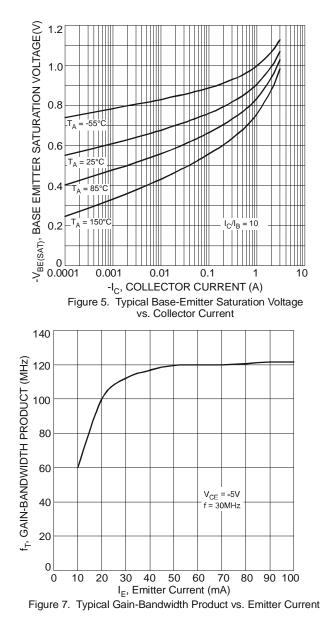
Notes: 5. Measured under pulsed conditions. Pulse width = 300μ s. Duty cycle $\leq 2\%$.

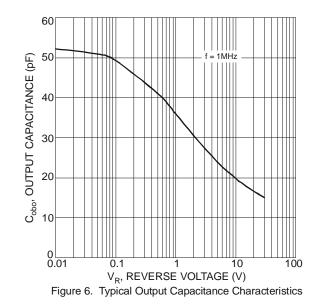






2DB1188P/Q/R

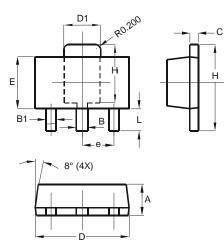






Package Outline Dimensions

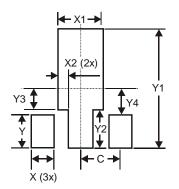
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT89				
Dim	Min	Max		
Α	1.40	1.60		
В	0.44	0.62		
B1	0.35	0.54		
С	0.35	0.44		
D	4.40	4.60		
D1	1.62	1.83		
E	2.29	2.60		
е	1.50 Typ			
н	3.94	4.25		
H1	2.63	2.93		
L	0.89	1.20		
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
С	1.500



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